

# MILITARY 8K x 8 CMOS EPROM KEY FEATURES

- Fast Access Time
   90 ns Over Full Mil Temp Range
- Low Power Consumption
- DESC SMD No. 85102

- EPI Processing
   Latch-Up Immunity Up to 200 mA
- Standard EPROM Pinout
- Military Temperature Operating Range

#### **GENERAL DESCRIPTION**

The WS27C64F is a High Performance 64K UV Erasable Electrically Programmable Read Only Memory. It is manufactured in an advanced CMOS technology which enables it to operate at high speeds and very low power over the full Military temperature operating range.

The WS27C64F is a direct drop-in replacement for the industry standard 27C64 and/or 2764 EPROMs. It was developed specifically for this purpose and requires no board or software modifications to complete the change.

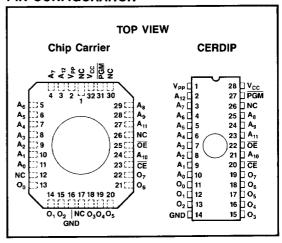
The WS27C64F is configured in the standard EPROM pinout which provides an easy upgrade path to the WS27C128F and WS27C256F.

#### **MODE SELECTION**

PINS	CE	ŌĒ	V <sub>PP</sub>	v <sub>cc</sub>	OUTPUTS
Read	V <sub>IL</sub>	$V_{IL}$	Vcc	$v_{cc}$	D <sub>OUT</sub>
Output Disable	Х	$V_{IH}$	V <sub>CC</sub>	$v_{cc}$	High Z
Standby	V <sub>IH</sub>	Х	V <sub>CC</sub>	$v_{cc}$	High Z
Program	V <sub>IL</sub>	$V_{IH}$	$V_{PP}$	$V_{CC}$	D <sub>IN</sub>
Program Verify	Х	V <sub>IL</sub>	$V_{PP}$	$V_{CC}$	D <sub>OUT</sub>
Program Inhibit	$V_{lH}$	V <sub>IH</sub>	$V_{PP}$	$v_{cc}$	High Z
Signature*	V <sub>IL</sub>	V <sub>IL</sub>	$V_{CC}$	$v_{cc}$	Encoded Data

 $<sup>\</sup>boldsymbol{X}$  can be either  $\boldsymbol{V}_{IL}$  or  $\boldsymbol{V}_{IH}.$ 

#### PIN CONFIGURATION



#### PRODUCT SELECTION GUIDE

PARAMETER	WS27C64F-90
Address Access Time (Max)	90 ns
Chip Select Time (Max)	90 ns
Output Enable Time (Max)	30 ns

<sup>\*</sup>For Signature,  $A_9 = 12V$ ,  $A_0$  is toggled, and all other addresses are at TTL low.  $A_0 = V_{II} = MFGR 23H$ ,  $A_0 = V_{IH} = DEVICE A8H$ .

## **ABSOLUTE MAXIMUM RATINGS\***

Storage Temperature	65° to +150°C
Voltage on Any Pin with	
Respect to GND	0.6V to +7V
V <sub>PP</sub> with respect to GND	0.6V to +14V
ESD Protection	>2000V

\*Notice: Stresses above those listed here may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect device reliability.

### **OPERATING RANGE**

RANGE	TEMPERATURE	V <sub>cc</sub>
Military	-55° to +125°C	+5V <u>+</u> 10%

## DC READ CHARACTERISTICS Over Operating Range with V<sub>PP</sub> = V<sub>CC</sub>

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	MAX	UNITS
V <sub>IL</sub>	Input Low Level	(Note 4)	-0.1	0.8	<b>V</b>
V <sub>IH</sub>	Input High Level	(Note 4)	2.0	$V_{CC} + 0.3$	٧
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 4 mA		0.4	V
V <sub>OH</sub>	Output High Voltage	$I_{OH} = -1 \text{ mA}$	2.4		٧
I <sub>SB1</sub>	V <sub>CC</sub> Standby Current (CMOS)	(Note 1)		200	μΑ
I <sub>SB2</sub>	V <sub>CC</sub> Standby Current (TTL)	(Note 2)		10	mA
I <sub>CC1</sub>	V <sub>CC</sub> Active Current (CMOS)	(Notes 1 and 3)		25	mA
I <sub>CC2</sub>	V <sub>CC</sub> Active Current (TTL)	(Notes 2 and 3)		35	mΑ
Ipp	V <sub>PP</sub> Supply Current	$V_{PP} = V_{CC}$		100	μΑ
V <sub>PP</sub>	V <sub>PP</sub> Read Voltage		V <sub>CC</sub> - 0.4	V <sub>cc</sub>	V
I <sub>LI</sub>	Input Load Current	V <sub>IN</sub> = 5.5V or Gnd	-10	10	μΑ
اره	Output Leakage Current	V <sub>OUT</sub> = 5.5 V or Gnd	-10	10	μA

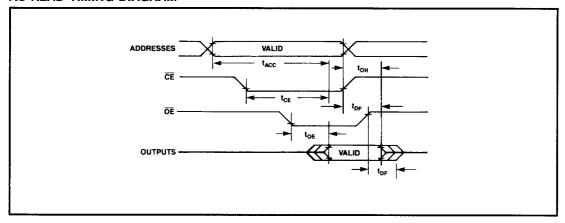
NOTES:

- 1. CMOS inputs: GND  $\pm$  0.3V or  $V_{CC}\pm0.3V.$
- 2. TTL inputs:  $V_{IL} \le 0.8V$ ,  $V_{IH} \ge 2.0V$ .
- 3. Add 3 mA/MHz for A.C. power component.
- 4. These are absolute voltages with respect to device ground pin and include all overshoots due to system and/or tester noise. Do not attempt to test these values without suitable equipment.

## AC READ CHARACTERISTICS Over Operating Range with V<sub>PP</sub> = V<sub>CC</sub>

CVMDOL	SYMBOL PARAMETER	WS270	UNITS	
STMBUL		MIN	MAX	O.U.I.S
t <sub>ACC</sub>	Address to Output Delay		90	
t <sub>CE</sub>	CE to Output Delay		90	l
toE	OE to Output Delay		30	ns
t <sub>DF</sub>	Output Disable to Output Float		30	
t <sub>OH</sub>	Address to Output Hold	0		

#### AC READ TIMING DIAGRAM



## CAPACITANCE (5) TA = 25°C, f = 1 MHz

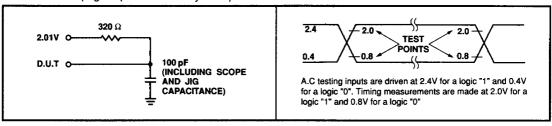
SYMBOL	PARAMETER	CONDITIONS	TYP (6)	MAX	UNITS
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	4	6	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	8	12	pF
C <sub>VPP</sub>	V <sub>PP</sub> Capacitance	$V_{PP} = 0V$	18	25	pF

NOTES: 5. This parameter is only sampled and is not 100% tested.

Typical values are for T<sub>A</sub> = 25°C and nominal supply voltages.

## TEST LOAD (High Impedance Test Systems)

## A.C. TESTING INPUT/OUTPUT WAVEFORM



NOTE: 7. Provide adequate decoupling capacitance as close as possible to this device to achieve the published A.C. and D.C. parameters. A 1.0 microfarad capacitor in parallel with a 0.1 microfarad capacitor connected between V<sub>CC</sub> and ground is recommended. Inadequate decoupling may result in access time degradation or other transient performance failures.

## PROGRAMMING INFORMATION

**DC CHARACTERISTICS** ( $T_A = 25 \pm 5^{\circ}C$ ,  $V_{CC} = 5.5V \pm 5\%$ ,  $V_{PP} = 13.5 \pm 0.5V$ )

SYMBOLS	PARAMETER	MIN	MAX	UNIT
lu	Input Leakage Current (V <sub>IN</sub> = V <sub>CC</sub> or Gnd)	-10	10	μА
Ірр	V <sub>PP</sub> Supply Current <u>During</u> Programming Pulse (CE = PGM = V <sub>IL</sub> )		60	mA
Icc	V <sub>CC</sub> Supply Current (Note 3)		50	mA
V <sub>OL</sub>	Output Low Voltage During Verify (I <sub>OL</sub> = 4 mA)		0.45	٧
V <sub>OH</sub>	Output High Voltage During Verify (I <sub>OH</sub> = -1mA)	2.4		٧

 $\textbf{NOTES:} \ \ \textbf{8.} \ \ \textbf{V}_{\text{CC}} \ \text{must} \ \text{be applied either coincidentally or before } \textbf{V}_{\text{PP}} \ \text{and } \ \text{remov} \underline{\text{ed}} \ \text{eit} \underline{\text{her co}} \text{incidentally or after } \textbf{V}_{\text{PP}}.$ 

9. Vpp must not be greater than 14 volts including overshoot. During CE = PGM = V<sub>IL</sub>, V<sub>PP</sub> must not be switched from 5 volts to 13.5 volts or vice-versa

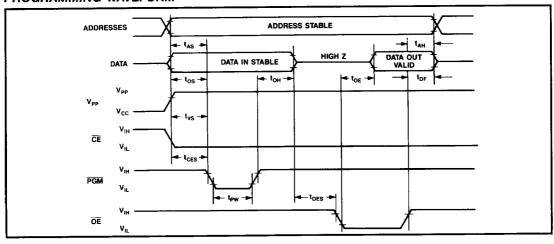
10. During power up the PGM pin must be brought high (≥V<sub>IH</sub>) either coincident with or before power is applied to V<sub>PP</sub>.

## **AC CHARACTERISTICS** $(T_A = 25 \pm 5^{\circ}C, V_{CC} = 5.5V \pm 5\%, V_{PP} = 13.5 \pm 0.5V)$

SYMBOLS	PARAMETER	MIN	TYP	MAX	UNITS
t <sub>AS</sub>	Address Setup Time	2			μs
t <sub>CES</sub>	Chip Enable Setup Time	2			μs
t <sub>OES</sub>	Output Enable Setup Time	2			μs
tos	Data Setup Time	2			μs
t <sub>AH</sub>	Address Hold Time	0			μs
t <sub>OH</sub>	Data Hold Time	2			μs
t <sub>DF</sub>	Chip Disable to Output Float Delay	0		130	ns
t <sub>OE</sub>	Data Valid From Output Enable			130	ns
t <sub>vs</sub>	V <sub>PP</sub> Setup Time	2			μs
t <sub>PW</sub>	PGM Pulse Width	1	3	10	ms

NOTE: 11. Single shot programming algorithms should use one 10 ms PGM pulse per byte.

#### PROGRAMMING WAVEFORM



## **ORDERING INFORMATION**

PART NUMBER	SPEED (ns)	PACKAGE TYPE	PACKAGE DRAWING	OPERATING TEMPERATURE RANGE	WSI MANUFACTURING PROCEDURE
WS27C64F-90CMB	90	32 Pad CLLCC	C2	Military	MIL-STD-883C
WS27C64F-90DMB	90	28 Pin CERDIP, 0.6"	D2	Military	MIL-STD-883C

NOTE: 12. The actual part marking will not include the initials "WS."

## PROGRAMMING/ERASURE/PROGRAMMERS

REFER TO PAGE 4-1